

## PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Yasuharu SEKI</td><td>10/05/2007</td></tr><tr><td>Kenji SHIBATA</td><td>10/01/2007</td></tr><tr><td>Takayuki KORI</td><td>10/01/2007</td></tr><tr><td>Tatsuya KONNO</td><td>10/09/2007</td></tr><tr><td>Rui YAMADA</td><td>10/04/2007</td></tr></tbody></table>	Name	Execution Date	Yasuharu SEKI	10/05/2007	Kenji SHIBATA	10/01/2007	Takayuki KORI	10/01/2007	Tatsuya KONNO	10/09/2007	Rui YAMADA	10/04/2007	
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RECEIVING PARTY DATA													
<table border="1"><tr><td>Name:</td><td>Sony Corporation</td></tr><tr><td>Street Address:</td><td>1-7-1 Konan, Minato-ku</td></tr><tr><td>City:</td><td>Tokyo</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>108-0075</td></tr></table>	Name:	Sony Corporation	Street Address:	1-7-1 Konan, Minato-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	108-0075			
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PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11846918</td></tr></tbody></table>	Property Type	Number	Application Number:	11846918									
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Application Number:	11846918												
CORRESPONDENCE DATA													
Fax Number: (703)413-2220 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone: (703) 413-3000													
Email: mkassaye@oblon.com													
Correspondent Name: Oblon, Spivak, et al.													
Address Line 1: 1940 Duke Street													
Address Line 4: Alexandria, VIRGINIA 22314													
ATTORNEY DOCKET NUMBER:	314083US												
NAME OF SUBMITTER:	Mesfin Kassaye												

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PATENT  
REEL: 019975 FRAME: 0172

**Total Attachments: 6**

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## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

COMMUNICATION SYSTEM, COMMUNICATION DEVICE, PROGRAM AND COMMUNICATION METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/846,918  
Filing Date: August 29, 2007

This assignment executed on the dates indicated below.

Yasuharu SEKI

Name of first or sole inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of first or sole inventor

Yasuharu Seki

Signature of first or sole inventor

Oct. 5, 2007

Date of this assignment

Kenji SHIBATA

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

Takayuki KORI

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

Tatsuya KONNO

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Rui YAMADA

Name of fifth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

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Date of this assignment

Kenji SHIBATA

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

*Kenji Shibata*

Signature of second inventor

*October 1st, 2007*

Date of this assignment

Takayuki KORI

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

*Takayuki Kori*

Signature of third inventor

*October 1, 2007*

Date of this assignment

Tatsuya KONNO

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Rui YAMADA

Name of fifth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

*Rui Yamada*

Signature of fifth inventor

*October 4, 2007*

Date of this assignment

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Execution date of U.S. Patent Application

Tokyo, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Kenji SHIBATA

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

Takayuki KORI

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

Tatsuya KONNO

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

Tatsuya Konno

Signature of fourth inventor

October 9, 2007

Date of this assignment

Rui YAMADA

Name of fifth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

PATENT

RECORDED: 10/17/2007

REEL: 019975 FRAME: 0179